

AMENDMENTS TO THE SPECIFICATION

Please amend the specification in accordance with 37 C.F.R. § 1.121(b)(1), as follows:

Replace the paragraph appearing in the specification at page 3, lines 16-27, with the following replacement paragraph:

In yet another aspect, a method of forming a semiconductor device package comprises: forming a lead frame from an electrically conductive material, including: forming a plurality of leads and a plurality of first interposers in the conductive material, and etching a bottom surface of the plurality of leads and the plurality of interposers, the etching defining a plurality of first surfaces on the leads ~~contacts~~; electrically connecting I/O pads on a semiconductor device to the plurality of leads; electrically connecting at least one passive device across pairs of first interposers in the plurality of interposers; and covering at least a portion of each of the lead frame, the semiconductor device, and the at least one passive device with a molding compound. The molding compound forms at least a portion of a first package face. The first surface of each lead is exposed at the first package face and at least a portion of each first interposer is spaced apart from the first package face.

Replace the paragraph appearing in the specification at page 9, lines 21-29, with the following replacement paragraph:

In the embodiment shown, the portion ~~portions~~ of each lead 16 exposed at the side surface 36 is separated from its associated bottom surface 38 by molding compound 28, which forms the entire bottom edge of the package 10. Alternatively, one or more of the leads ~~contacts~~ 16 may be configured such that the portion of the lead 16 exposed at the side surface 36 connects with the bottom surface 38 of the lead 16 at the bottom edge of the package 10. In this embodiment, the one or more lead 16 forms a portion of the bottom edge of the package 10. In a typical arrangement, only the bottom surfaces 38 of the leads 16 will be used for connection to an external electrical circuit. However, the bottom surfaces 60 of the support posts 58 may also be connected to an external circuit if desired.